



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET



- ▶ EMC SMD Top View
- ▶ 3838 1.85t Series
- ▶ Infrared (IR) 950nm

**NOF66S99BF**



Release Date: 05 September 2024 Version: A1.0



### 3838 1.85t Series

**RoHS Compliant**



**AUTOMOTIVE AEC-Q102**

#### FEATURES:

- **Package:** Black Ceramic Dual Junction SMT Package
- **Forward Current:** 1000mA
- **Pulse Forward Current (max.):** 3A
- **Forward Voltage (typ.):** 3.0V
- **Radiant Power (typ.):** 1500mW@1A
- **Radiant Intensity (typ.):** 560mW/sr@1A
- **Colour:** Infrared (IR)
- **Peak Wavelength (typ.):** 950nm
- **Viewing Angle:** 120°
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+85°C
- **Grouping Parameters:**
  - Forward Voltage
  - Radiant Power
  - Peak Wavelength
- **Soldering Methods:** Reflow Soldering
- **MSL Level:** MSL 2 according to J-STD020
- **Corrosion Robustness Class:** 3B
- **Packing:** 12mm tape with max.800/reel,  $\phi$ 178mm (7")

#### APPLICATIONS:

- Automotive
- Security Camera
- Motion Detection
- Night Viewer
- Surveillance
- Data Communication

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

| Parameter                                      | Symbol           | Ratings          | Unit |
|--|------------------|------------------|------|
| DC Forward Current                             | I <sub>F</sub>   | 1000             | mA   |
| Power Consumption                              | P <sub>tot</sub> | 3.4              | W    |
| Pulse Forward Current                          | I <sub>PF</sub>  | 3                | A    |
| Reverse Voltage                                | V <sub>R</sub>   | 5                | V    |
| Reverse Current @5V                            | I <sub>R</sub>   | 10               | μA   |
| Junction Temperature                           | T <sub>j</sub>   | 115              | °C   |
| Thermal Resistance Junction to Solder Point    | R <sub>th</sub>  | typ. 4.5; typ. 9 | K/W  |
| Electrostatic Discharge (HBM: MIL-STD-883 C 2) | ESD              | 2                | kV   |
| Operating Temperature                          | T <sub>OPR</sub> | -40~+85          | °C   |
| Storage Temperature                            | T <sub>STG</sub> | -40~+85          | °C   |
| Soldering Temperature                          | T <sub>SOL</sub> | 260              | °C   |

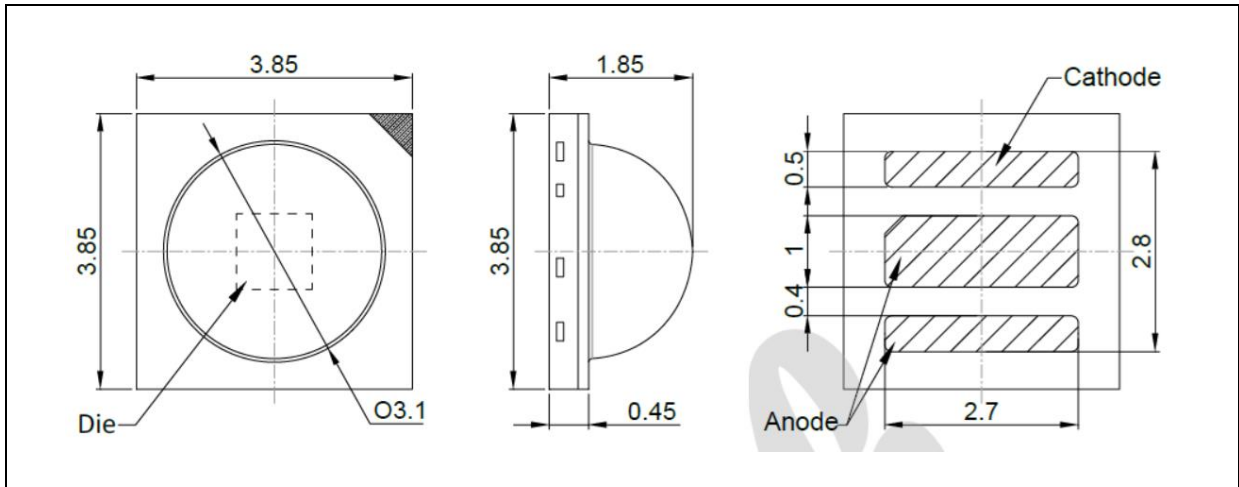
### Electrical & Optical Characteristics (Ta=25°C, I<sub>F</sub>=1A, t<sub>p</sub>=10ms)

| Parameter          | Symbol            | Values |      |      | Unit  | Test Condition                              |
|--------------------|-------------------|--------|------|------|-------|---|
|                    |                   | Min.   | Typ. | Max. |       |   |
| Forward Voltage    | V <sub>F</sub>    | 2.8    | 3.0  | 3.4  | V     | I <sub>F</sub> =1A<br>t <sub>p</sub> =100μs |
| Radiant Power      | Φ <sub>e</sub>    | 1300   | 1500 | 1700 | mW    | I <sub>F</sub> =1A<br>t <sub>p</sub> =100μs |
| Radiant Intensity  | I <sub>e</sub>    | 460    | 560  | 660  | mW/sr | I <sub>F</sub> =1A<br>t <sub>p</sub> =100μs |
| Peak Wavelength    | λ <sub>p</sub>    | ---    | 950  | ---  | nm    | I <sub>F</sub> =1A                          |
| Spectral Bandwidth | Δλ                | ---    | 35   | ---  | nm    | I <sub>F</sub> =1A                          |
| Viewing Angle      | 2θ <sub>1/2</sub> | ---    | 120  | ---  | deg   | I <sub>F</sub> =1A                          |

1. Radiant Power (P<sub>o</sub>) ±10%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle(2θ<sub>1/2</sub>) ±10°

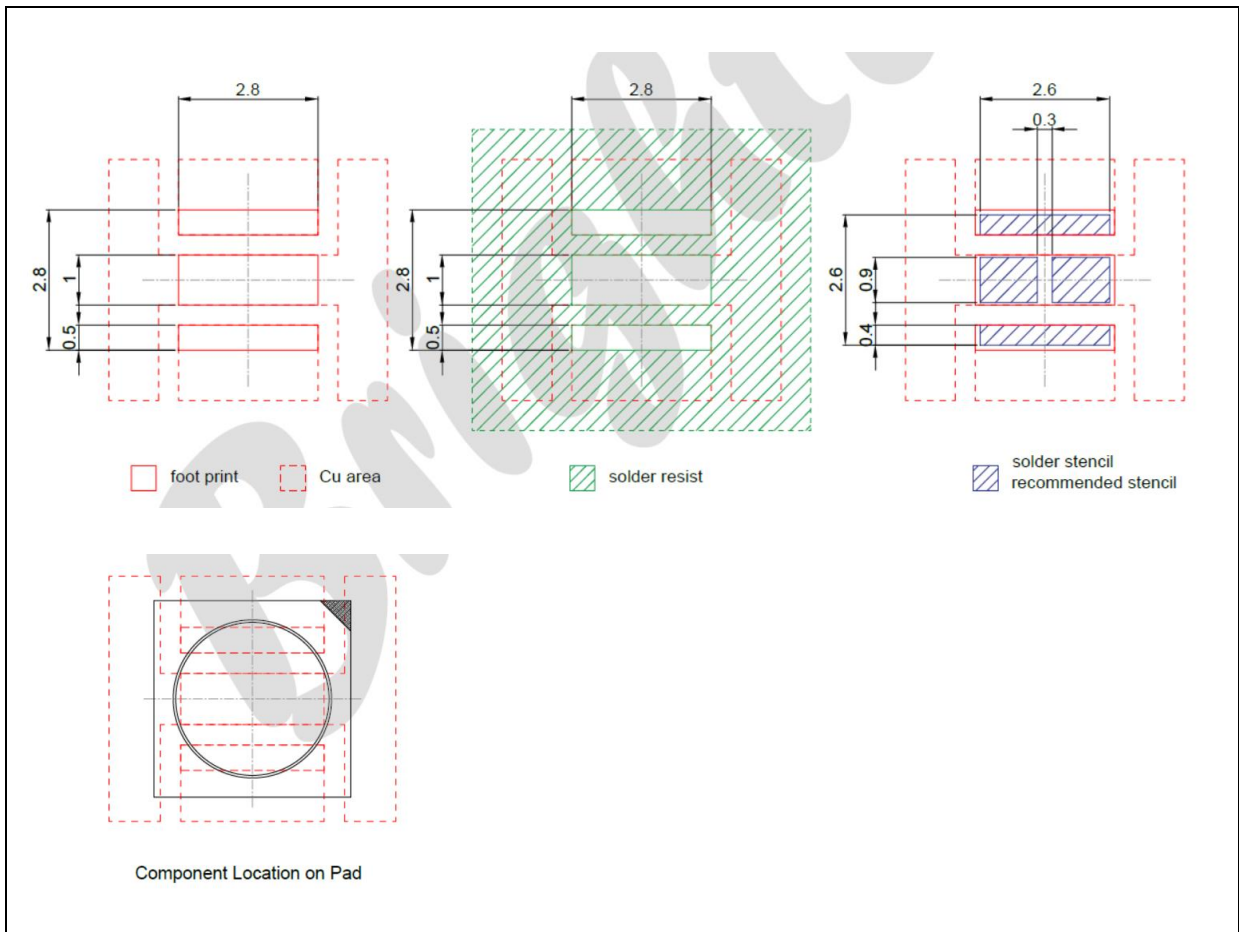
## OUTLINE DIMENSION:

### Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.05\text{mm}$ , unless otherwise noted.

### Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1\text{mm}$  with angle tolerance  $\pm 0.5^\circ$ .

**BINNING GROUPS:**


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 Forward Voltage Classifications ( $I_F=1A$ ;  $t_p=10ms$ ):

| Code | Min. | Max. | Unit |
|------|------|------|------|
| DF   | 2.8  | 3.4  | V    |

 Radiant Power Classifications ( $I_F=1A$ ;  $t_p=10ms$ ):

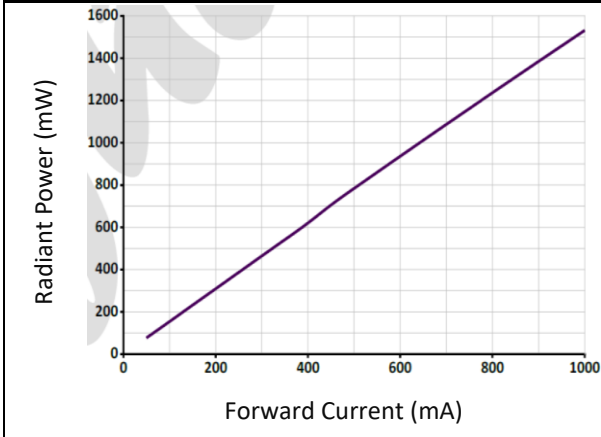
| Code | Min. | Max. | Unit |
|------|------|------|------|
| PB3A | 1300 | 1500 | mW   |
| PB5A | 1500 | 1700 |      |

 Peak Wavelength Classifications ( $I_F=1A$ ;  $t_p=10ms$ ):

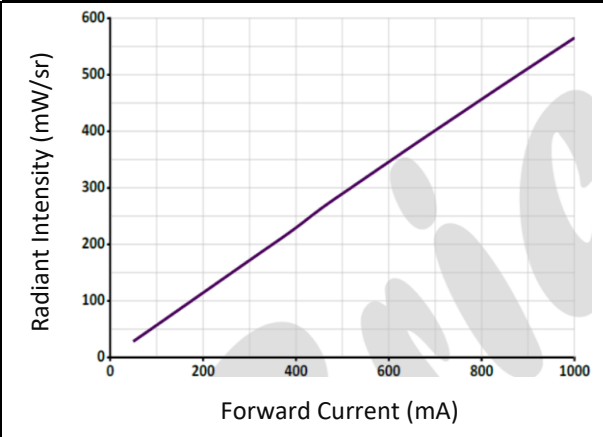
| Code | Min. | Max. | Unit |
|------|------|------|------|
| F3   | 940  | 970  | nm   |

## ELECTRO-OPTICAL CHARACTERISTICS:

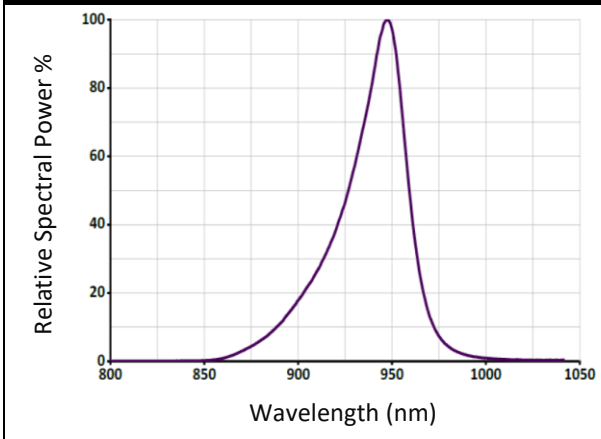
Radiant Power v.s. Forward Current



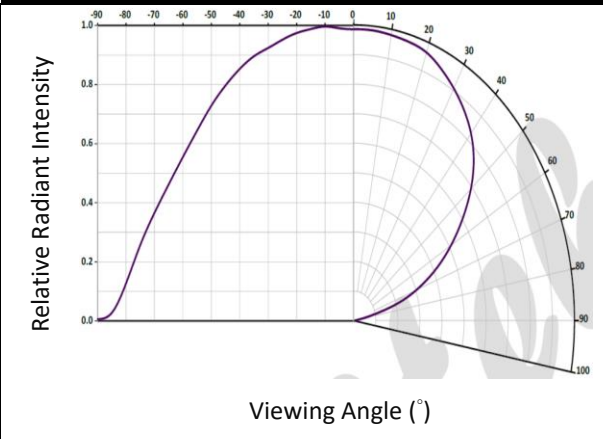
Radiant Intensity v.s. Forward Current



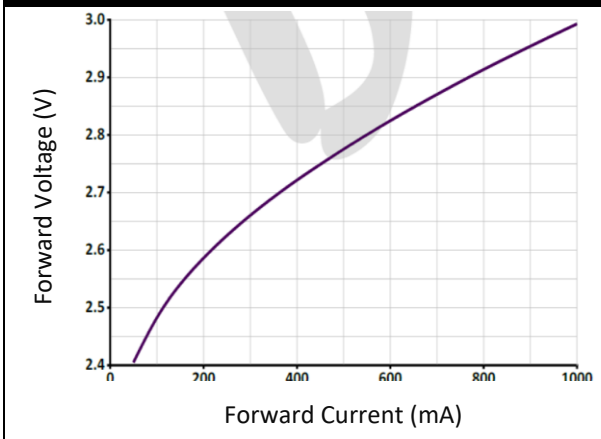
Relative Spectral Power v.s. Wavelength



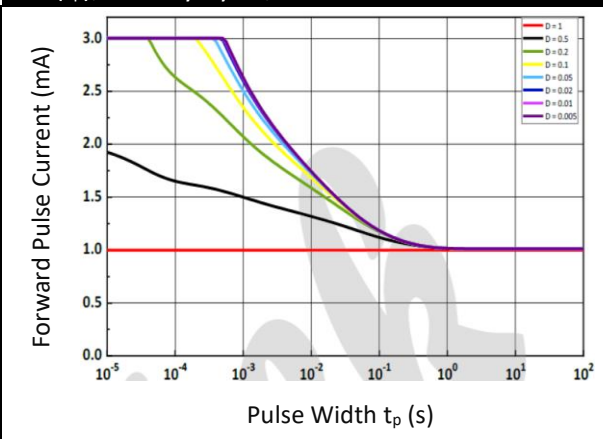
Directive Radiation (L=0)



Forward Current v.s. Forward Voltage



Permissible Pulse Handling Capability  
 $I_F = f(t_p)$ ;  $D = \text{Duty Cycle}$ ;  $T_s = 85^\circ\text{C}$

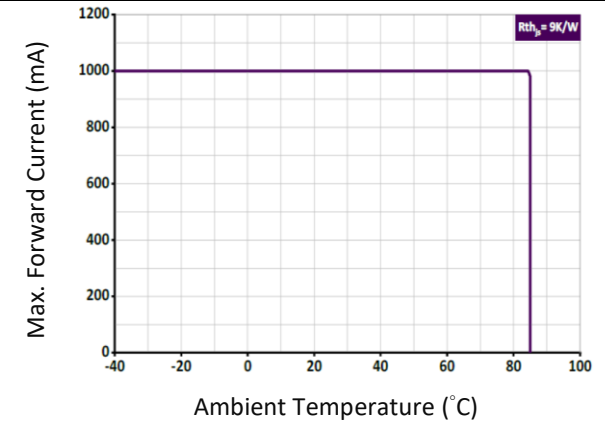


## ELECTRO-OPTICAL CHARACTERISTICS:

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### Permissible Forward Current

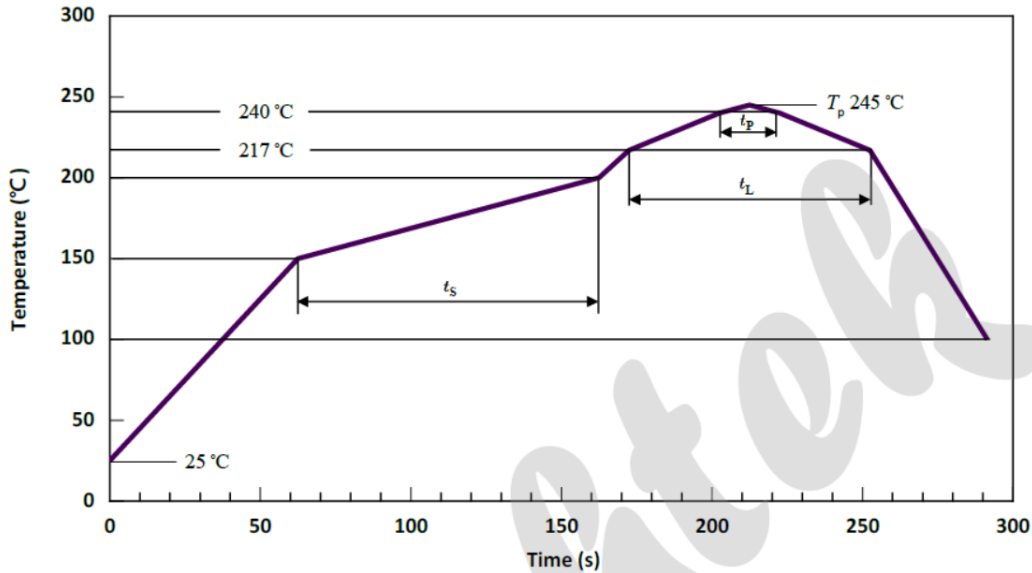
$$I_{F(\max)} = f(T_s); R_{thjs} = 9K/W$$





## RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



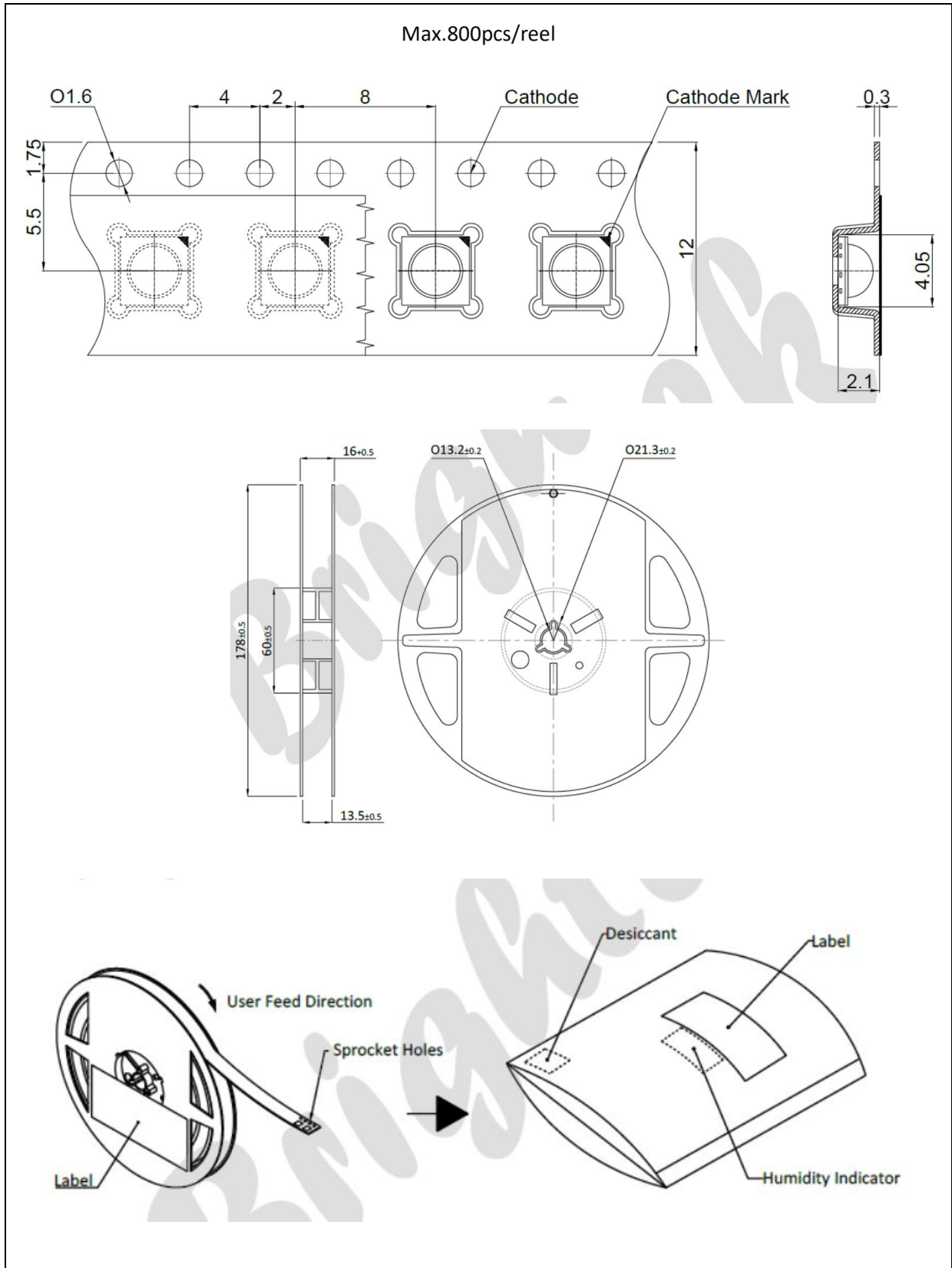
| Profile Feature   | Symbol | Pb-Free (SnAgCu) Assembly |                |         | Unit |
|---|--------|---------------------------|----------------|---------|------|
|   |        | Minimum                   | Recommendation | Maximum |      |
| Ramp-up rate to preheat<br>25 °C to 150 °C                        |        |                           | 2              | 3       | K/s  |
| Time $t_s$<br>$T_{smin}$ to $T_{smax}$                            | $t_s$  | 60                        | 100            | 120     | s    |
| Ramp-up rate to peak<br>$T_{smax}$ to $T_p$                       |        |                           | 2              | 3       | K/s  |
| Liquidus temperature  | $T_L$  |                           | 217            |         | °C   |
| Time above liquidus temperature                                   | $t_L$  |                           | 80             | 100     | s    |
| Peak temperature  | $T_p$  |                           | 245            | 260     | °C   |
| Time within 5 °C of the specified<br>peak temperature $T_p - 5$ K | $T_p$  | 10                        | 20             | 30      | s    |
| Ramp-down Rate<br>$T_p$ to 100 °C                                 |        |                           | 3              | 4       | K/s  |
| Time<br>25 °C to $T_p$  |        |                           |                | 480     | s    |

Note:

1. Maximum reflow soldering: 2 times.
2. Recommended soldering temperature is 245°C. The maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

## PACKING SPECIFICATION:

Reel Dimension:





## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

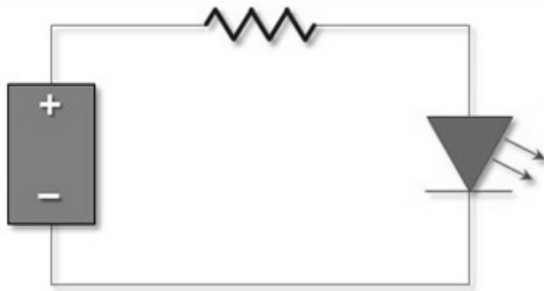
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

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| Version | Date       | Summary of Revision |
|---------|------------|---------------------|
| A1.0    | 05/09/2024 | Datasheet set-up.   |